

General Description

It combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

Features

- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

Application

- BLDC Motor driver
- DC-DC
- Battery protection

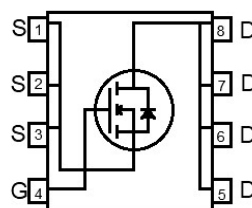
Ordering Information:

Part NO.	ZMS040N04HNC
Marking	ZMS040N04H
Packing Information	REEL TAPE
Basic ordering unit (pcs)	3000

Absolute Maximum Ratings ($T_C=25^{\circ}\text{C}$)

Parameter	Symbol	Conditions	Value	Unit
Drain-Source Voltage	V_{DS}		40	V
Gate-Source Voltage	V_{GS}		± 20	V
Continuous Drain Current	I_D	$T_C=25^{\circ}\text{C}$	75	A
	I_D	$T_C=75^{\circ}\text{C}$	67	A
	I_D	$T_C=100^{\circ}\text{C}$	58	A
Pulsed Drain Current	I_{DM}	Pulsed; $t_p \leq 10 \mu\text{s}$; $T_{mb} = 25^{\circ}\text{C}$;	300	A
Total Power Dissipation	P_D	$T_C=25^{\circ}\text{C}$	75	W
Total Power Dissipation	P_D	$T_A=25^{\circ}\text{C}$	3.3	W
Operating Junction Temperature	T_J		-55 to +175	$^{\circ}\text{C}$
Storage Temperature	T_{STG}		-55 to +175	$^{\circ}\text{C}$
Single Pulse Avalanche Energy	E_{AS}	$L=0.1\text{mH}$, $V_{GS}=10\text{V}$, $R_g=25\Omega$,	40	mJ
		$L=0.5\text{mH}$, $V_{GS}=10\text{V}$, $R_g=25\Omega$,	84	mJ
ESD Level (HBM)	CLASS 1C			

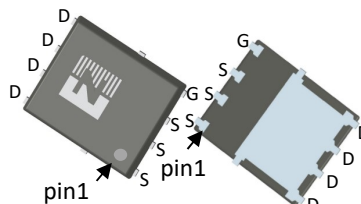
Product Summary



$$V_{DS} = 40\text{V}$$

$$R_{DS(ON)} = 4\text{m}\Omega$$

$$I_D = 75\text{A}$$



DFN5*6



•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}		-	2.0	°C/W
Thermal resistance, junction-ambient	$R_{thJA}^{①}$		-	45	°C/W
Soldering temperature (total time<10s)	T_{sold}		-	260	°C

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	40			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	2.0	2.7	4.0	V
Drain-Source Leakage Current	I_{DSS}	$V_{GS}=0V, V_{DS}=40V$			1.0	μA
Gate- Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$			100	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=14A$		4	5.5	m Ω
Forward Transconductance	g_{FS}	$V_{GS}=5V, I_{SD}=4A$		7		S
Diode Forward Voltage	V_{FSD}	$V_{GS}=0V, I_{SD}=14A$			1.3	V

•Dynamic characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Input capacitance	C_{iss}	$f=1MHz, V_{DS}=25V$	-	908	-	pF
Output capacitance	C_{oss}		-	244	-	
Reverse transfer capacitance	C_{rss}		-	10	-	
Gate Resistance	R_g	$f=1MHz$	-	1.2		Ω
Total gate charge	Q_g	$V_{DD}=15V, I_D=14A, V_{GS}=10V$	-	14	-	nC
Gate - Source charge	Q_{gs}		-	3.2	-	
Gate - Drain charge	Q_{gd}		-	3.5	-	
Turn-ON Delay time	$t_{D(on)}$	$V_{GS}=10V, V_{DS}=15V, R_G=3.3\Omega, I_D=20A$	-	5	-	ns
Turn-ON Rise time	t_r		-	10	-	ns
Turn-Off Delay time	$t_{D(off)}$		-	8	-	ns
Turn-Off Fall time	t_f		-	3	-	ns
Reverse Recovery Time	t_{rr}	$V_{DD}=20V, di_S/dt=100A/\mu s, I_S=50A$	-	30	-	ns
Reverse Recovery Charge	Q_{rr}		-	21	-	nC

Fig.1 Gate-Charge Characteristics

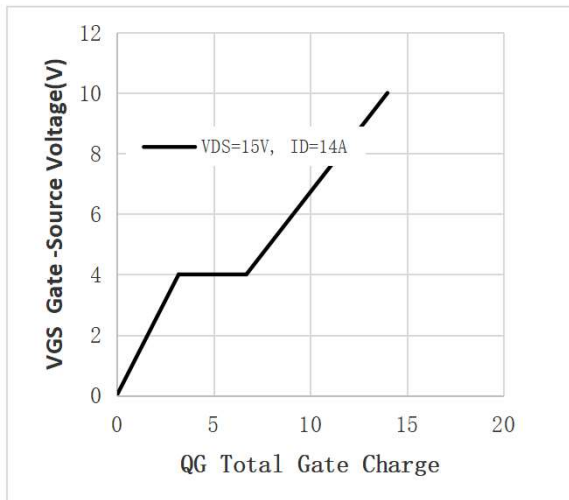


Fig.2 Capacitance Characteristics

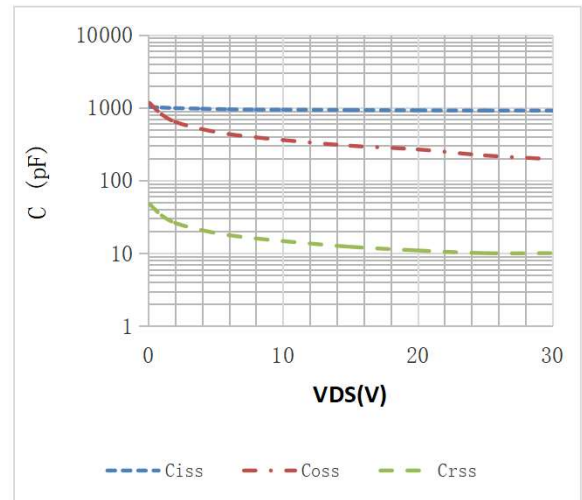


Fig.3 Power Dissipation

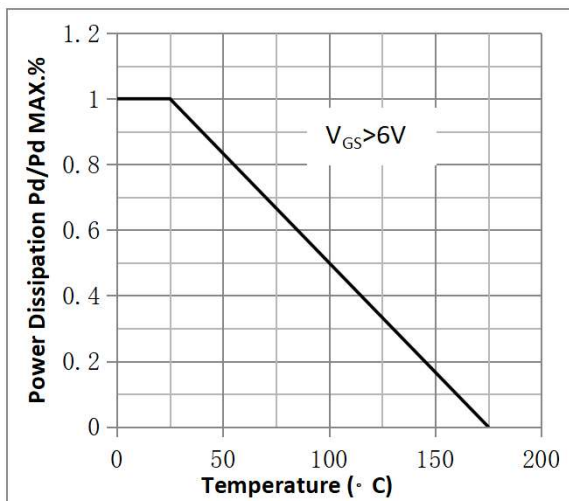


Fig.4 Typical output Characteristics

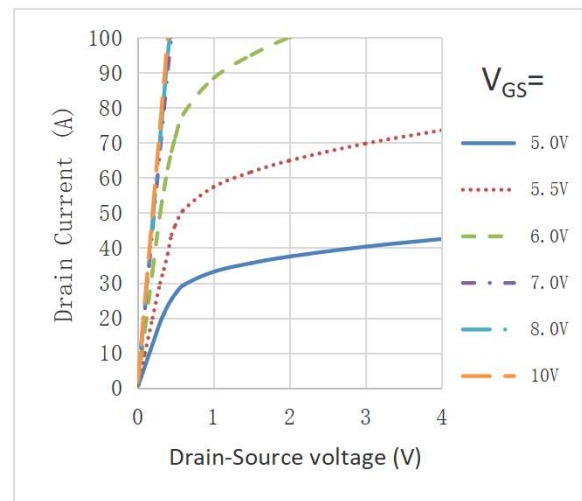


Fig.5 Threshold Voltage V.S Junction Temperature

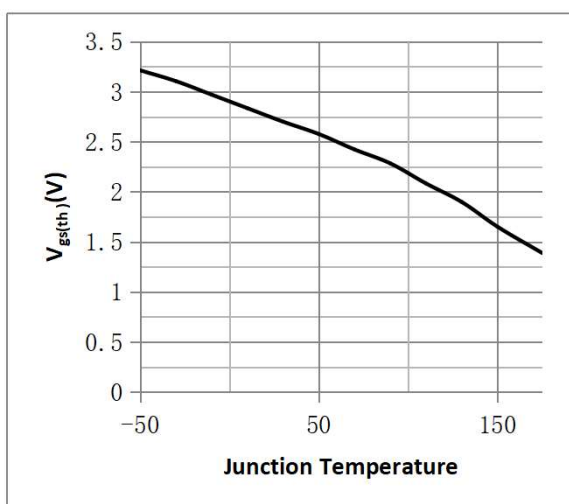


Fig.6 Resistance V.S Drain Current

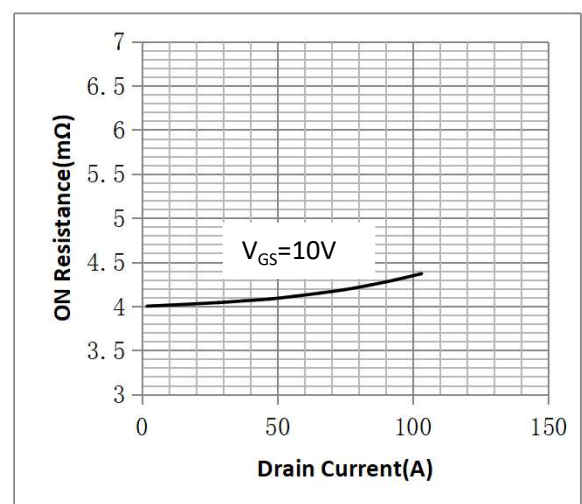


Fig.7 On-Resistance VS Gate Source Voltage

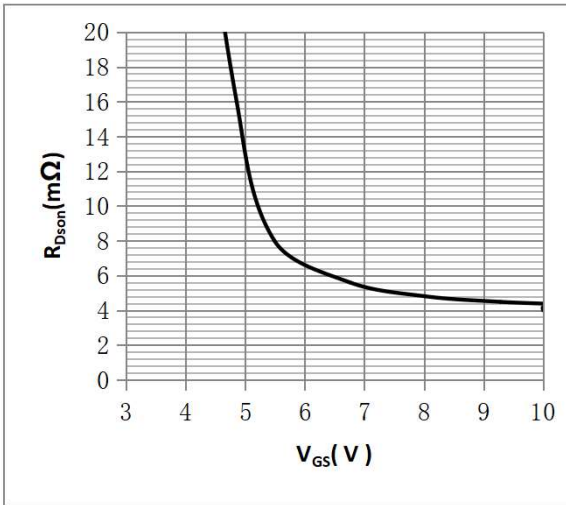


Fig.8 On-Resistance V.S Junction Temperature

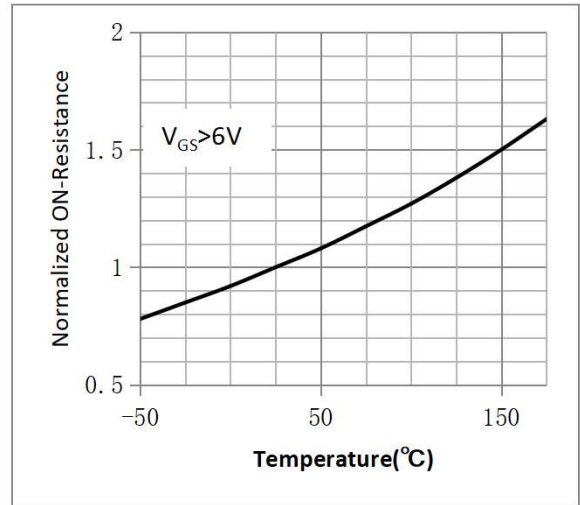


Figure 9. Diode Forward Voltage vs. Current

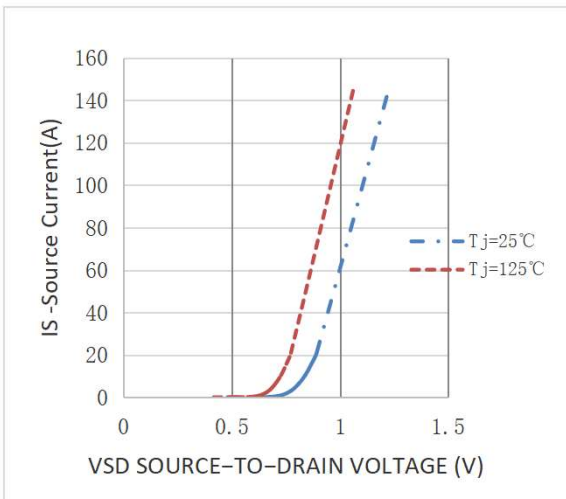


Figure 10. Transfer Characteristics

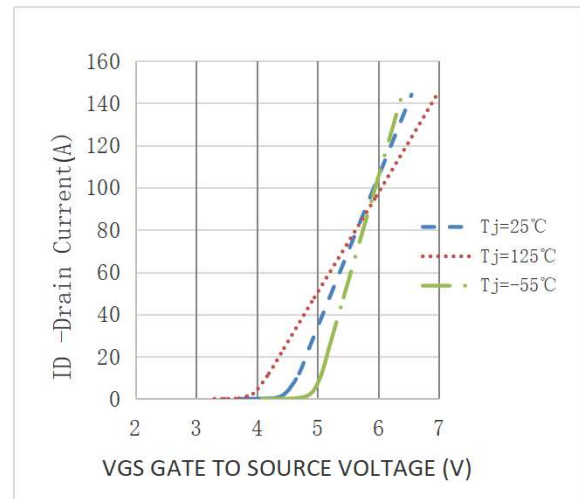


Fig.11 Safe Operating Area

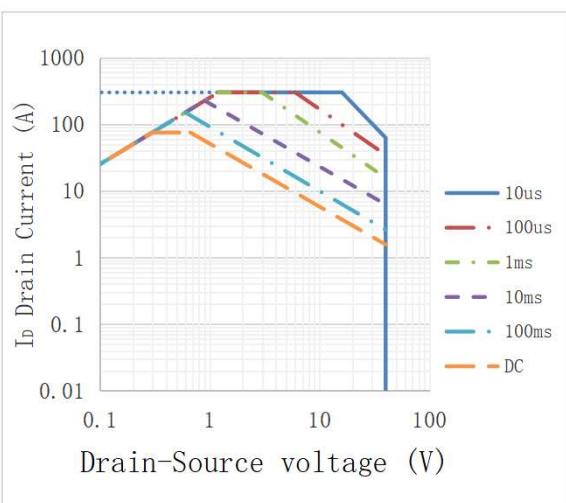
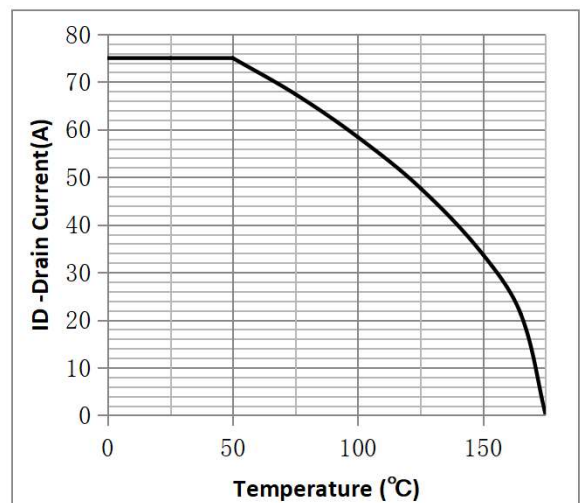
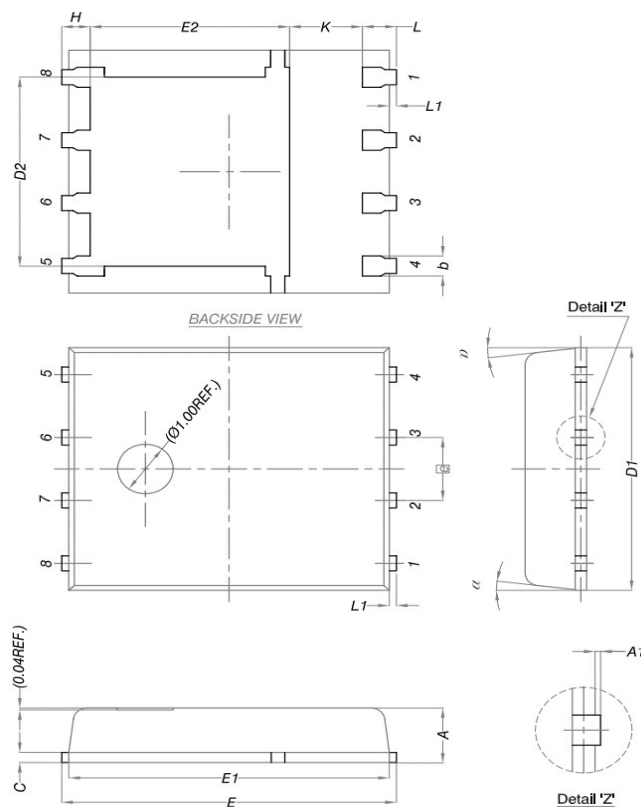


Fig.12 I_D vs. Junction Temperature^②



•DFN5*6 Package Outline



MILLIMETERS			
DIM	MIN.	NOM.	MAX.
A	0.90	1.00	1.15
A1	0	—	0.05
b	0.33	0.41	0.51
C	0.20	0.25	0.30
D1	4.80	4.90	5.00
D2	3.61	3.81	3.96
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.38	3.58	3.78
e	1.27 BSC		
H	0.41	0.51	0.61
K	1.10		
L	0.42	0.61	0.71
L1	0.06	0.13	0.20
α	0		12

Note:

- ① Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate;
- ② Practically the current will be limited by PCB, thermal design and operating temperature. $V_{GS}=10V$.

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Revision History

Version	Date	Change
A	2022.11.6	New